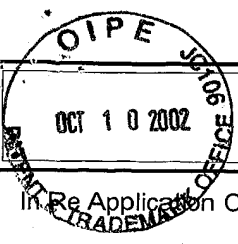


2827



TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
PHN16-224A

In Re Application Of: **Friedl et al.**

Serial No. 09/024,637	Filing Date 02/17/1998	Examiner Dinh, T.	Group Art Unit 2827
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Title: **SYNTHETIC RESIN CAPPING LAYER ON A PRINTED CIRCUIT**

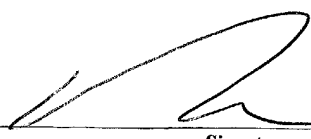
TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is: **Amendment in 4 pages**
Separate Markup Sheet in 2 pages

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in the above identified application.

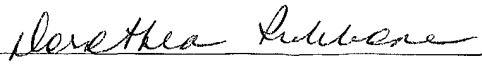
- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **500999** as described below. A duplicate copy of this sheet is enclosed.
 - ☐ Charge the amount of _____
 - ☒ Credit any overpayment.
 - ☒ Charge any additional fee required.



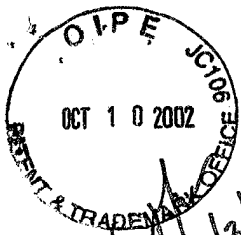
Signature

Dated: **October 3, 2002**

Ronald A. D'Alessandro
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(518) 449-0044

I certify that this document and fee is being deposited on 10/03/2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.
 <i>Signature of Person Mailing Correspondence</i>
Dorothea Rubbone <i>Typed or Printed Name of Person Mailing Correspondence</i>

CC:



DOCKET NO. PHN16-224A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Friedl et al. ✓

Examiner: Dinh, T.

Application No.: 09/024,637 ✓

Art Unit: 2827

Filed: 02/17/1998 ✓

For: SYNTHETIC RESIN CAPPING LAYER
ON A PRINTED CIRCUIT

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Washington D.C. 20231

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#25/F
Amend
J. McInnis
10/28/02

AMENDMENT

Sir:

In response to the Office Action of July 3, 2002, Applicants hereby respond as follows:

IN THE CLAIMS

Please amend claims 8 and 11 to appear as set forth below. The changes made thereto are shown in the attached Separate Markup Sheet.

FI
8. (Four-Times Amended) A printed circuit which is provided with a synthetic resin capping layer, said circuit comprising a printed circuit board having at least one electric component, and the capping layer comprising a foam-forming reactive injection-moulding material exhibiting a variation of mechanical properties in a direction at right